Isaac Newton is reported to have said in 1676: "If I have seen further, it is by standing on the shoulders of giants."

IEEE offers you another such opportunity in 2017.

IEEE REBOOTING COMPUTING WEEK
DISCOVERY, REINVENTION, APPLICATION

6-10 November 2017 • Washington, D.C. USA
LEADING THE FUTURE

We are continually challenged to react to an endless stream of new technology events. Here is an opportunity to better anticipate those events by seeing further over the technology horizon. What should we expect as we enter a new era of computing that is currently un-imaginable?

Join IEEE at Rebooting Computing Week this November in Washington, D.C. to hear keynote speakers such as Bernie Meyerson, IBM’s Chief Innovation Officer, provide insights into the direction and pace of the computing evolution. We will provide you with an interdisciplinary look at what to expect next year, in 5 years and even for the next 20-30 years of computing.

CONFERENCE THEME & TOPICS

NEW COMPUTING ELEMENTS
- Extending Moore’s Law
- Beyond CMOS devices
- Spin-based Electronics
- Foundry and Lithography Advances
- Future of Design Automation

NEW SOFTWARE AND ALGORITHMS
- Beyond Von Neumann Software Issues
- Hardware-software Interfaces

NEW WAYS TO COMPUTE
- Beyond Von Neumann Architectures
- Brain-inspired Computing
- Energy-efficient Computing
- Quantum Computing
- Approximate Computing
- Error-tolerant Computing
- Superconducting Computing
- Biological Computing
- Optical Computing
- Cellular Automata

SECURITY
COMMERCIAL AND SCIENTIFIC APPLICATIONS

REBOOTINGCOMPUTING.IEEE.ORG/REBOOTING-COMPUTING-WEEK
KEYNOTE AND PLENARY SPEAKERS

Join IEEE as we convene great thinkers around the discussion of what we should expect as we enter a new era of computing. Hear from trailblazers in hardware, software, low energy, and high performance computing.

ICRC

Prof. Luis Ceze  
University of Washington

“Borrowing from Nature to Build Better Computers”

Prof. Margaret Martonosi  
Princeton University

“End of Moore’s Law Challenges and Opportunities: Computer Architecture Perspectives”

Prof. Robert Schoelkopf  
Yale Quantum Institute

“The Prospects for Quantum Computing with Superconducting Circuits”

Prof. Karlheinz Meier  
University of Heidelberg

“Continuously Learning Neuromorphic Systems with High Biological Realism”

Dr. Hava Siegelmann  
Program Manager, DARPA Microsystems Technology Office

(Not Pictured)

Dr. Barbara Helland  
Associate Director of Advanced Scientific Computing Research, DOE

Industry Summit

R. Stanley Williams  
Senior Fellow and Founding Director of the Quantum Science Research Laboratory Hewlett-Packard

Mark Papermaster  
Chief Technology Officer AMD

Dan Hutcheson  
CEO and Chairman VLSIresearch inc.

Dr. Bernie Meyerson  
IBM Fellow and Chief Innovation Officer - IBM
# PATRONAGE OPPORTUNITIES

*Reach your target audience:*

More than 400 global attendees throughout the week  
ICRC 2016 - 39% from academia, 11% from government, and 50% from industry/research  
Showcase your leading-edge technology, recruit professionals, and discover new ideas for future products  
Hear from trailblazers in hardware, software, low energy, and high performance computing

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ADDITIONAL OPPORTUNITIES AVAILABLE

**BANQUET SPONSOR: $4,000 -- ONE EXCLUSIVE OPPORTUNITY**
- Logo and name on display at banquet
- Opportunity to briefly address attendees
- Two (2) full registrations
- Acknowledgement in program

**PLENARY SPONSOR: $3,000 -- FOUR EXCLUSIVE OPPORTUNITIES**
- Logo and name on display at Plenary
- Opportunity to briefly address attendees
  - Acknowledgement in program

**LUNCH SPONSOR: $2,000 -- TWO EXCLUSIVE OPPORTUNITIES**
- Logo and name on display at Lunch
- Opportunity to briefly address attendees
  - Acknowledgement in program

**BREAK SPONSOR: $1,000 -- FOUR EXCLUSIVE OPPORTUNITIES**
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  - Acknowledgement in program

Choose from the list of offerings, or contact us to discuss customized opportunities:
Terence Martinez – t.c.martinez@ieee.org
Jinjun Xiong – jinjun@us.ibm.com
Beth Surmont – b.surmont@ieee.org
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